

Load Switch with Low On-Resistance

■ GENERAL DESCRIPTION

The XC8102 series is a low ON resistance load switch IC with ON/OFF control and output current protection which integrates a P-channel MOSFET.

By connecting the XC8102 to the output pin of a step-down DC/DC converter, the CE pin controls ON/OFF for each distribution switch to deliver power per requirements and maximize total power efficiency. As a result, the XC8102 helps to extend battery life and product operation time.

The series contains a current limit and protection circuit so these are not required externally unlike discrete circuit solutions where MOSFETs and resistors are used.

When a low signal is input to the CE pin, the series enters stand-by mode. Even where a load capacitor is connected to the output pin during stand-by, the electric charge stored at the load capacitor is discharged through the internal switch. As a result, the V_{OUT} pin voltage falls quickly to the V_{SS} level.

The series contains over current protection with fold-back current circuitry which operates as over current protection and short circuit protection for the output pin.

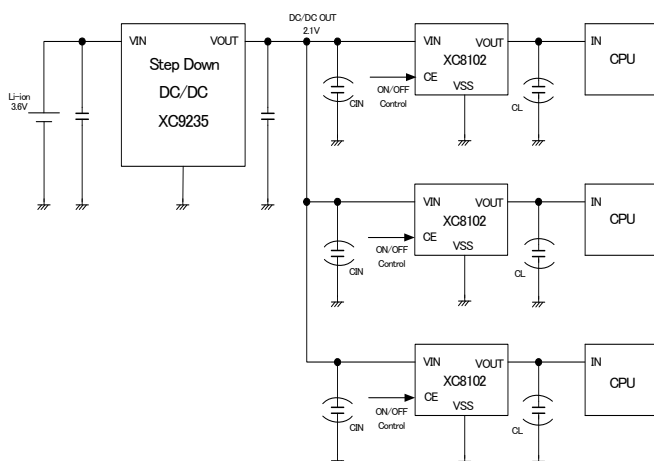
■ APPLICATIONS

- Mobile phones, Smart phones
- Digital still cameras, Digital video cameras
- Portable game consoles
- Portable equipment

■ FEATURES

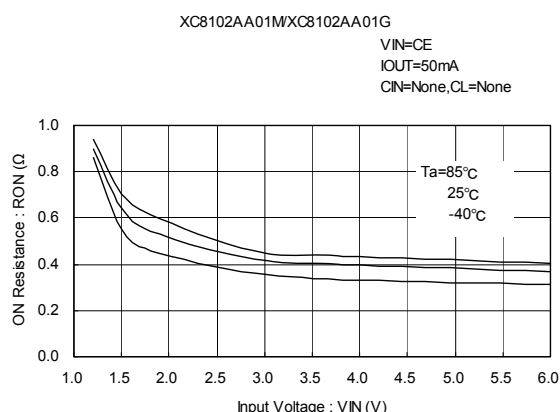
On Resistance	: 0.28Ω@ $V_{IN}=6.0V$ (TYP.) : 0.31Ω@ $V_{IN}=4.0V$ (TYP.) : 0.35Ω@ $V_{IN}=2.9V$ (TYP.) : 0.52Ω@ $V_{IN}=1.8V$ (TYP.) : 0.60Ω@ $V_{IN}=1.5V$ (TYP.) : 0.80Ω@ $V_{IN}=1.2V$ (TYP.)
Input Voltage Range	: 1.2V~6.0V
Power Consumption	: 3.0 μA@ $V_{IN}=1.2V$: 3.6 μA@ $V_{IN}=2.9V$: 4.0 μA@ $V_{IN}=6.0V$
Stand-by Current	: 0.1 μA
Protection Circuit	: Current limit(Output Current) 480mA (TYP.) ($1.8 \leq V_{IN} \leq 6.0V$) : Short-circuit Protection, Short current= 30mA (TYP.)
ON/OFF Function	: High Active Enable
High-Speed Discharge Function	
Operating Temperature Range	: -40°C~+85°C
Packages	: USP-4, SSOT-24, SOT-25 USPN-4
Environmentally Friendly	: EU RoHS Compliant, Pb Free

■ TYPICAL APPLICATION CIRCUIT

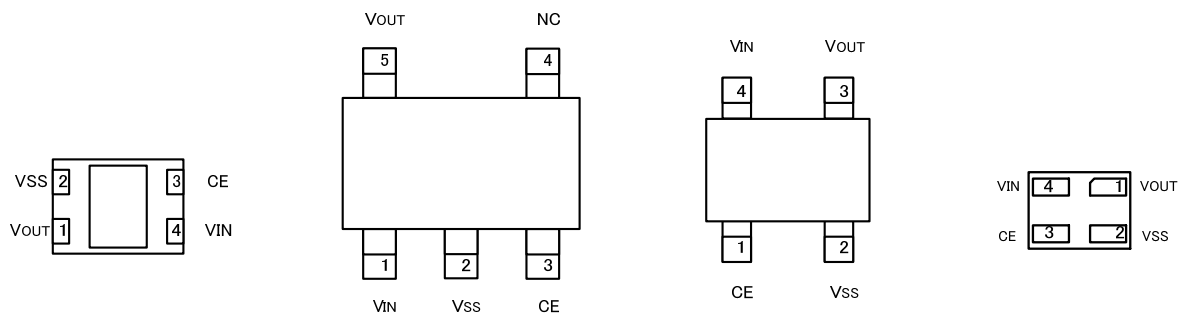


■ TYPICAL PERFORMANCE CHARACTERISTICS

● On Resistance vs. Input Voltage



PIN CONFIGURATION



USP-4
(BOTTOM VIEW)

SOT-25
(TOP VIEW)

SSOT-24
(TOP VIEW)

USPN-4
(BOTTOM VIEW)

*The heat dissipation pad of the USP-4 package is recommended to solder as shown in the recommended mount pattern and metal mask pattern for mounting strength. The heat dissipation pad should be electrically opened or connected to the V_{SS} (No. 2) pin.

PIN ASSIGNMENT

PIN NUMBER				PIN NAME	FUNCTIONS
USP-4	SOT-25	SSOT-24	USPN-4		
4	1	4	4	V _{IN}	Power Input
1	5	3	1	V _{OUT}	Output
2	2	2	2	V _{SS}	Ground
3	3	1	3	CE	ON/OFF Control
—	4	—	—	NC	No Connection

PRODUCT CLASSIFICATION

Ordering Information

XC8102①②③④⑤⑥-⑦^(*)

DESIGNATOR	DESCRIPTION	SYMBOL	DESCRIPTION
①	CE pin logic	A	CE High active
②	C _L Discharge Function	A	Output capacitor (C _L) auto-discharge function integrated
③④	Internal Standard Number	01	Fixed
⑤⑥-⑦	Packages Taping Type ^(*)	GR-G	USP-4
		MR-G	SOT-25
		NR-G	SSOT-24
		7R-G	USPN-4

^(*) The "-G" suffix indicates that the products are Halogen and Antimony free as well as being fully RoHS compliant.

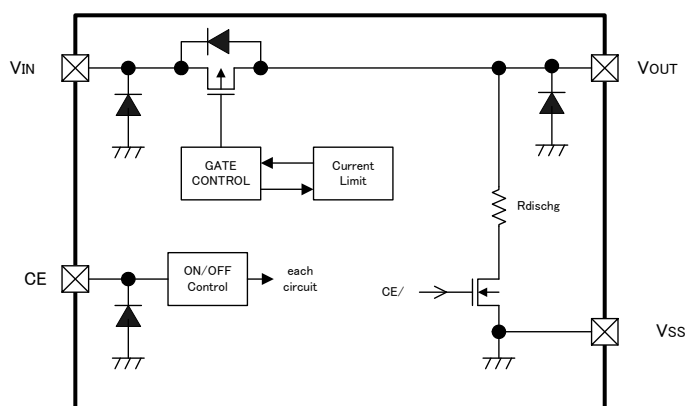
^(*) The device orientation is fixed in its embossed tape pocket. For reverse orientation, please contact your local Torex sales office or representative. (Standard orientation: ⑤R-⑦, Reverse orientation: ⑤L-⑦)

FUNCTION CHART

SERIES	CE	IC OPERATIONAL STATUS ON/OFF
XC8102AA01	High	ON
	Low	OFF

BLOCK DIAGRAM

●XC8102AA Series



* Diodes inside the circuit are an ESD protection diode and a parasitic diode.

ABSOLUTE MAXIMUM RATINGS

PARAMETER		SYMBOL	RATINGS	UNITS
Input Voltage		V_{IN}	$V_{SS}-0.3 \sim +6.5$	V
Output Current		I_{OUT}	850*	mA
Output Voltage		V_{OUT}	$V_{SS}-0.3 \sim V_{IN}$	V
CE Input Voltage		V_{CE}	$V_{SS}-0.3 \sim +6.5$	V
Power Dissipation	USP-4	Pd	120	mW
	SSOT-24		150	
	SOT-25		250	
	USPN-4		100	
Operating Temperature Range		T_{opr}	$-40 \sim +85$	$^{\circ}\text{C}$
Storage Temperature Range		T_{stg}	$-55 \sim +125$	$^{\circ}\text{C}$

* Please make sure that I_{OUT} is less than $P_d / (V_{IN} - V_{OUT})$

ELECTRICAL CHARACTERISTICS

●XC8102AA Series

Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUITS
Input Voltage	V_{IN}		1.2	-	6.0	V	-
On Resistance (SSOT-24/USPN-4)	R_{ON}	$V_{IN}=6.0V, V_{CE}=V_{IN}$	-	0.28	0.425	Ω	①
		$V_{IN}=4.0V, V_{CE}=V_{IN}$	-	0.31	0.475		
		$V_{IN}=2.9V, V_{CE}=V_{IN}$	-	0.35	0.475		
		$V_{IN}=1.8V, V_{CE}=V_{IN}$	-	0.52	0.625		
		$V_{IN}=1.5V, V_{CE}=V_{IN}$	-	0.60	0.80		
		$V_{IN}=1.2V, V_{CE}=V_{IN}$	-	0.80	1.60		
On Resistance (SOT-25/USP-4)	R_{ON}	$V_{IN}=6.0V, V_{CE}=V_{IN}$	-	0.35	0.475	Ω	①
		$V_{IN}=4.0V, V_{CE}=V_{IN}$	-	0.38	0.525		
		$V_{IN}=2.9V, V_{CE}=V_{IN}$	-	0.43	0.525		
		$V_{IN}=1.8V, V_{CE}=V_{IN}$	-	0.59	0.675		
		$V_{IN}=1.5V, V_{CE}=V_{IN}$	-	0.67	0.85		
		$V_{IN}=1.2V, V_{CE}=V_{IN}$	-	0.87	1.65		
Supply Current	I_{DD}	$V_{IN}=6.0V, V_{CE}=V_{IN}, V_{OUT}=OPEN$	-	4.0	7.0	μA	②
		$V_{IN}=4.0V, V_{CE}=V_{IN}, V_{OUT}=OPEN$	-	3.8	6.5		
		$V_{IN}=2.9V, V_{CE}=V_{IN}, V_{OUT}=OPEN$	-	3.6	6.3		
		$V_{IN}=1.8V, V_{CE}=V_{IN}, V_{OUT}=OPEN$	-	3.4	5.7		
		$V_{IN}=1.5V, V_{CE}=V_{IN}, V_{OUT}=OPEN$	-	3.2	5.5		
		$V_{IN}=1.2V, V_{CE}=V_{IN}, V_{OUT}=OPEN$	-	3.0	4.9		
Stand-by Current	I_{STBY}	$V_{IN}=6.0V, V_{CE}=V_{SS}, V_{OUT}=OPEN$	-	0.01	0.10	μA	②
Switch Leakage Current	I_{LEAK}	$V_{IN}=6.0V, V_{CE}=V_{SS}, V_{OUT}=0V$	-	0.01	0.10	μA	②
Current Limit	I_{LIM}	$V_{IN} \geq 2.9V, V_{OUT} = V_{IN} - 0.8V$	400	480	-	mA	①
		$1.8V \leq V_{IN} < 2.9V, V_{OUT} = V_{IN} - 0.6V$	400	480	-		
		$1.5V \leq V_{IN} < 1.8V, V_{OUT} = 1.2V$	200	-	-		
		$1.2V \leq V_{IN} < 1.5V, V_{OUT} = 1.0V$	90	-	-		
Short Circuit Current	I_{SHORT}	$V_{CE}=V_{IN}, V_{OUT}=0V$	-	30	75	mA	①
CE High Level Voltage	V_{CEH}		1.1	-	6.0	V	③
CE Low Level Voltage	V_{CEL}		-	-	0.3	V	③
CE High Level Current	I_{CEH}	$V_{CE}=V_{IN}$	-0.1	-	0.1	μA	③
CE Low Level Current	I_{CEL}	$V_{CE}=V_{SS}$	-0.1	-	0.1	μA	③
C_L Auto-Discharge Resistance	R_{DCHG}	$V_{IN}=4.0V, V_{OUT}=4.0V, V_{CE}=V_{SS}$	380	480	570	Ω	④
Turn On Time ^{(*)1}	$t_{DLY(ON)}$	$V_{IN}=4.0V, V_{CE}=0.3V \rightarrow 1.2V, R_L=80\Omega$, without C_{IN}, C_L	-	8.5	18	μs	⑤
Turn Off Time ^{(*)2}	$t_{DLY(OFF)}$	$V_{IN}=4.0V, V_{CE}=1.2V \rightarrow 0.3V, R_L=80\Omega$, without C_{IN}, C_L	-	3.0	7.5	μs	⑤

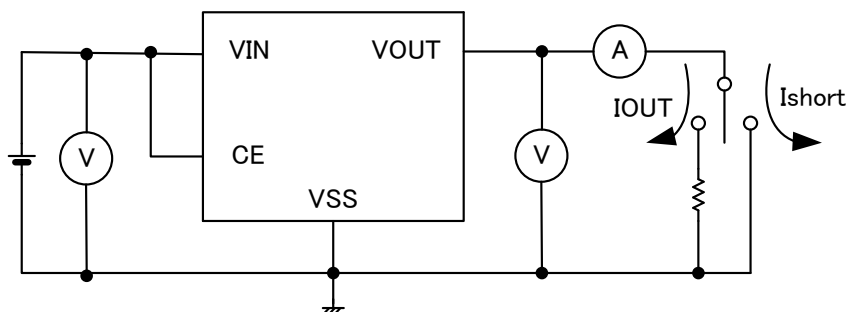
NOTE:

*1: Time to reach 90% of V_{OUT} after V_{CE} entering the V_{CEH} threshold.

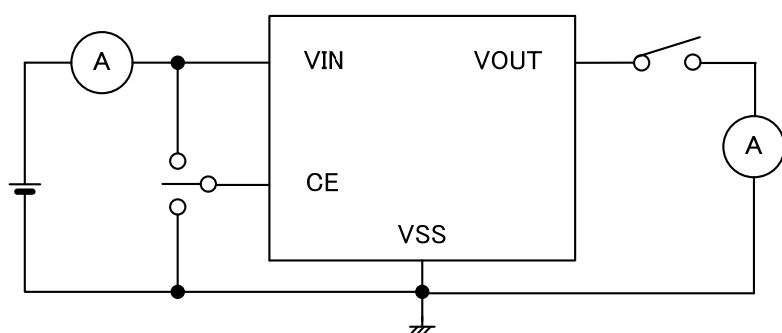
*2: Time to fall to 10% of V_{OUT} after V_{CE} entering the V_{CEL} threshold.

■ TEST CIRCUITS

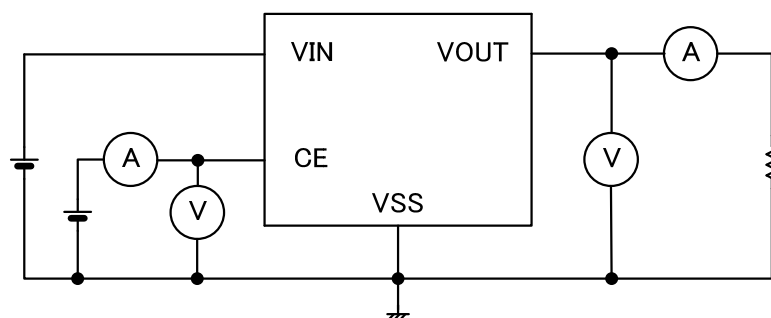
Circuit ①



Circuit ②

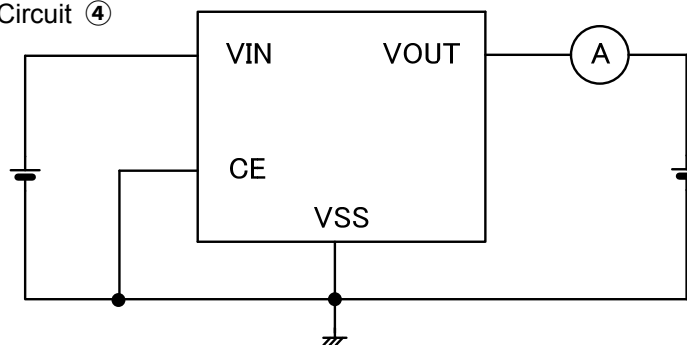


Circuit ③

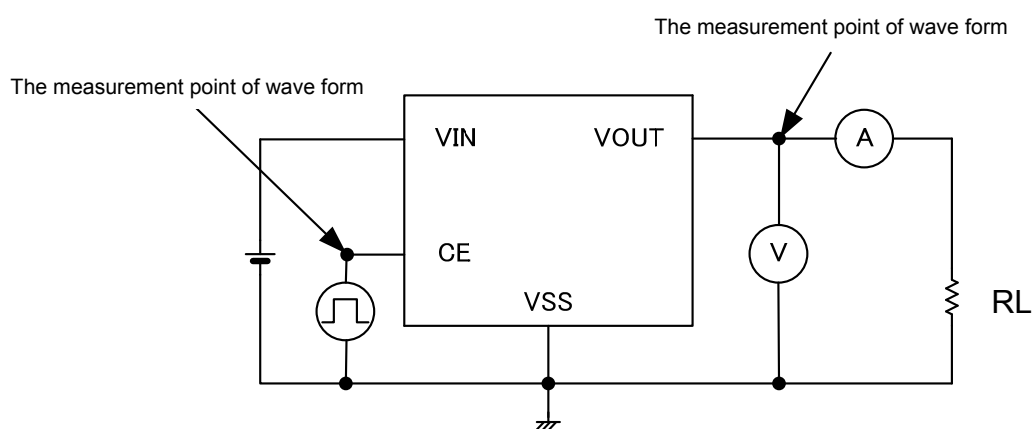


TEST CIRCUITS (Continued)

Circuit ④



Circuit ⑤



■ OPERATIONAL EXPLANATION

<CE Pin>

The XC8102 enables an output P-channel MOSFET switch and the IC internal circuitry to turn off by the signal to the CE pin. In the shutdown mode, the V_{OUT} pin will be pulled down to the V_{SS} by the C_L auto-discharge function.

The output voltage becomes unstable when the CE pin is opened. If the input voltage to the CE pin is within the specified threshold voltages, the logic is fixed and the XC8102 will operate normally. However, supply current may increase as a result of the shoot-through current of internal circuitry when the medium level voltage is input to the CE pin.

<Input/Output Capacitor>

The XC8102 works well without an input and output capacitors. Also, an output capacitor of the power source can be used as an input capacitor of the XC8102 and a bypass capacitor of the driving IC can be used as an output capacitor of the XC8102.

<CL Auto-Discharge Function>

The XC8102AA contains a C_L auto-discharge resistor and an N-channel transistor between the V_{OUT} pin and the V_{SS} pin. The device quickly discharge the electric charge in the output capacitor (C_L) when a low signal to the CE pin is input to turn off a whole IC circuit. The C_L auto-discharge resistance is set at $480\ \Omega$ ($V_{OUT}=4.0V$ TYP. @ $V_{IN}=4.0$). Discharge time of the output capacitor (C_L) is determined by a CL auto-discharge resistor value (R_{dischg}) and an output capacitor value. Time constant τ is defined as ($\tau = C \times R_{dischg}$). Output voltage after starting discharge can be calculated by the following formula.

$$V = V_{OUT} \times e^{-t/\tau}, \text{ or } t = \tau \ln (V_{OUT} / V)$$

V: Output voltage after starting discharge,

V_{OUT} : Output voltage,

t : Discharge time,

τ : Output discharge resistor value R_{dischg} × Output capacitor (C_L) value C

<Current Limiter, Short-Circuit Protection>

The XC8102 series contains a constant current limiter and fold-back current circuitry. The constant current limiter operates to limit output current and the fold-back current circuitry operates as short circuit protection for the output pin.

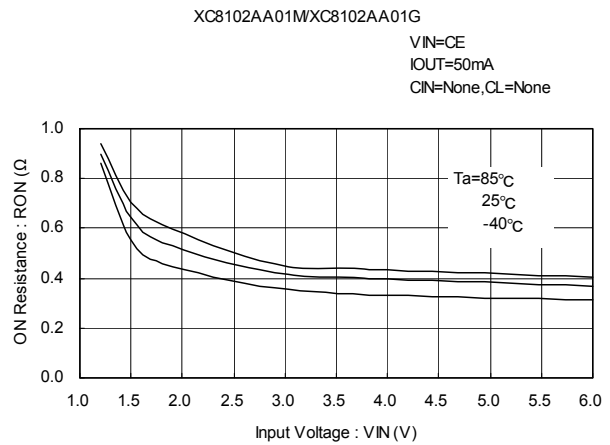
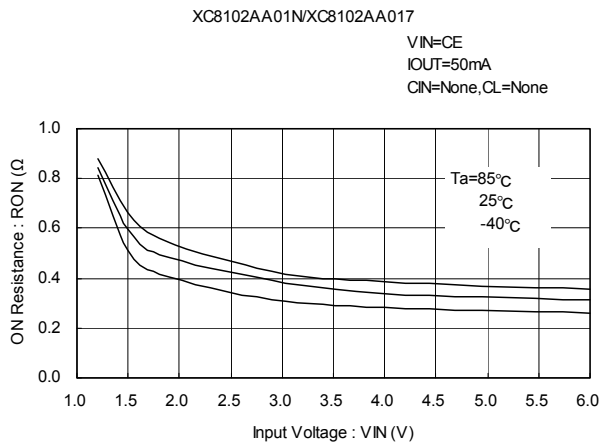
When the load current reaches the limit current, the constant current limiter operates and the output voltage drops. The output voltage further, then the fold-back current circuitry operates to decrease the output current. When the output pin is short-circuited to the ground, the output current drops and maintains a flow about 30mA.

■ NOTES ON USE

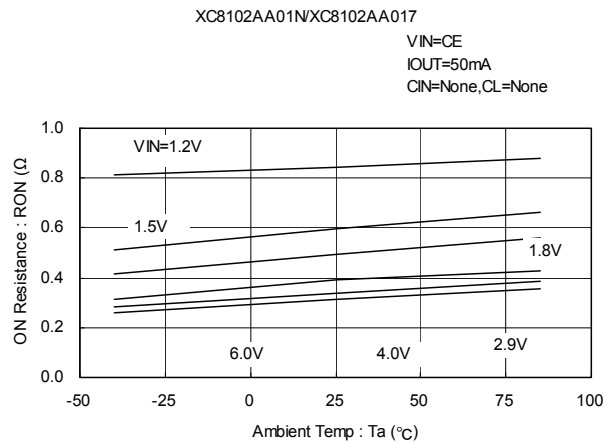
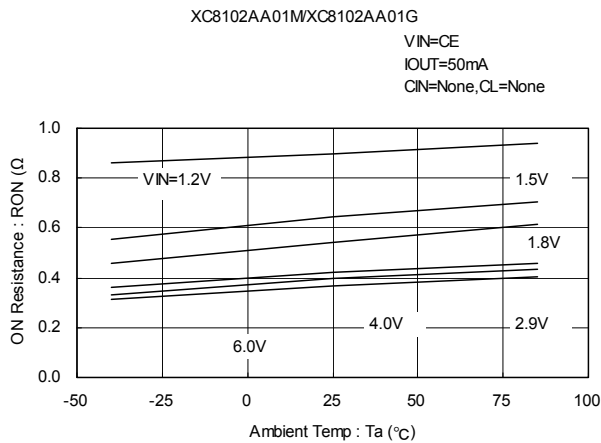
1. Please use this IC within the stated absolute maximum ratings. Operation beyond these limits may cause degrading or permanent damage to the device.
2. The X8102 goes into an undefined operation when the CE pin is left open. The CE pin shall be tied to low or high level.
3. V_{OUT} pin voltage should not be applied beyond the V_{IN} pin voltage.
The IC may get damage due to the reverse current toward the V_{IN} pin.
4. Current limit function is integrated. However, power dissipation may be beyond the limit before starting a fold-back current protection when used in high temperature. For the power dissipation of each package, please refer to the graphs of Package Power vs. Operating Temperature in page 15 to 18.

TYPICAL PERFORMANCE CHARACTERISTICS

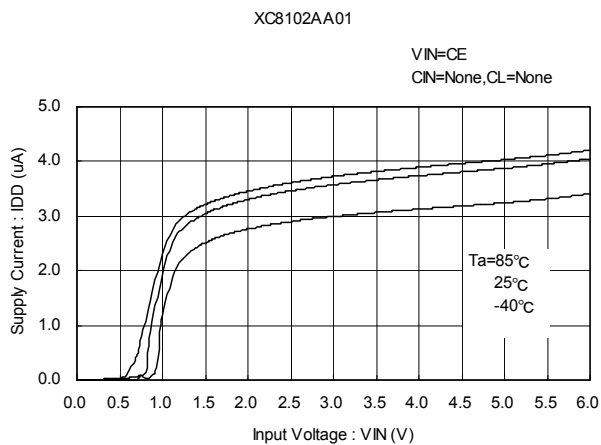
(1) ON Resistance vs. Input Voltage



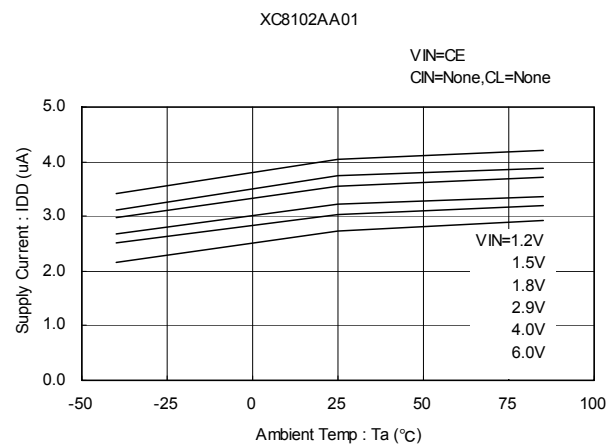
(2) ON Resistance vs. Ambient Temperature



(3) Supply Current vs. Input Voltage

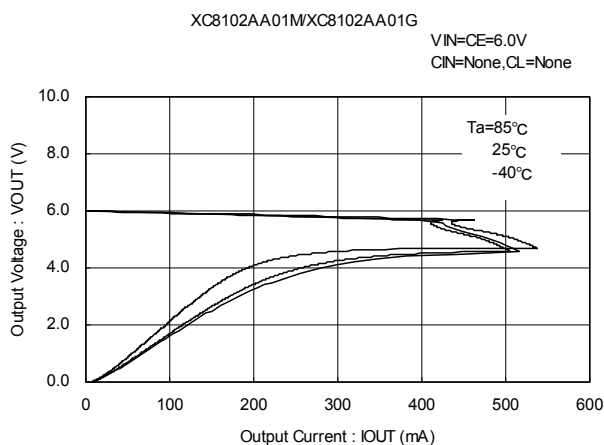
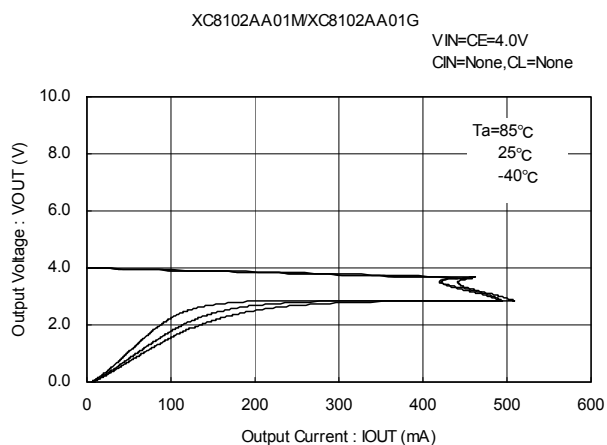
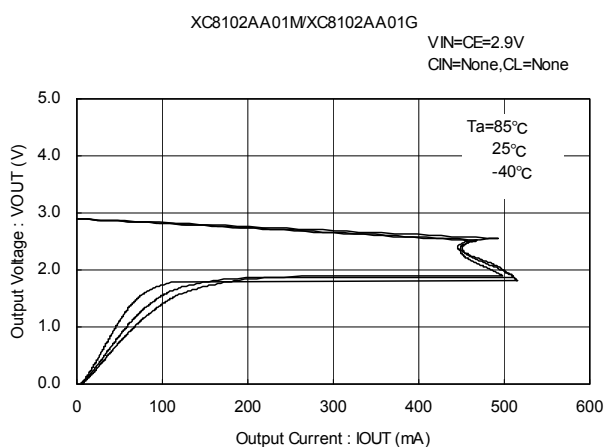
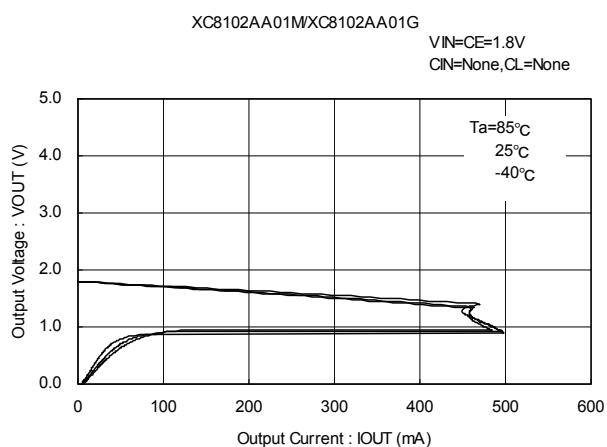
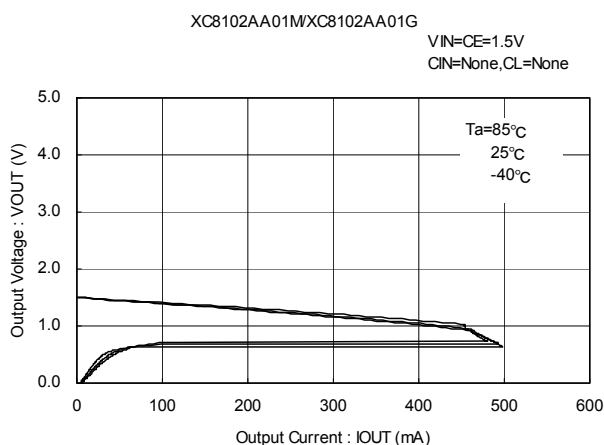
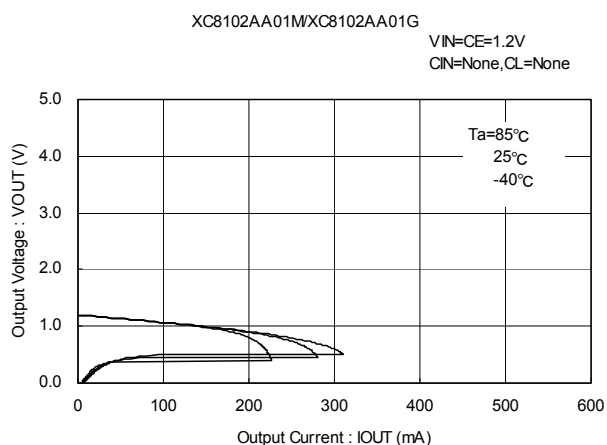


(4) Supply Current vs. Ambient Temperature



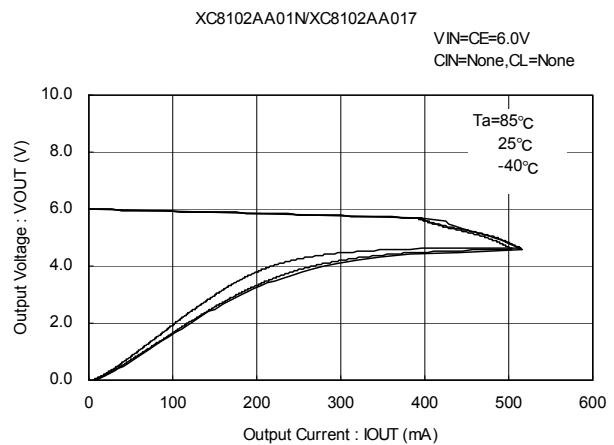
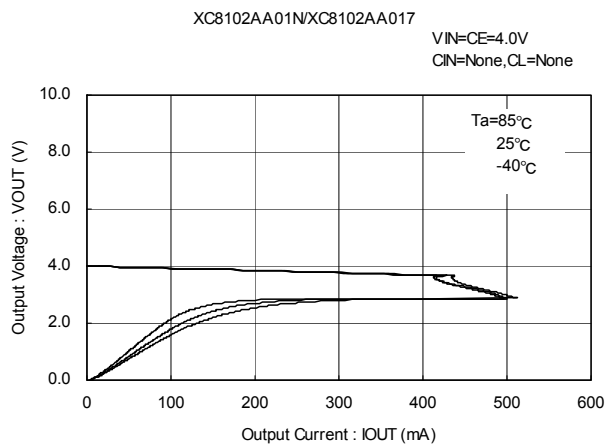
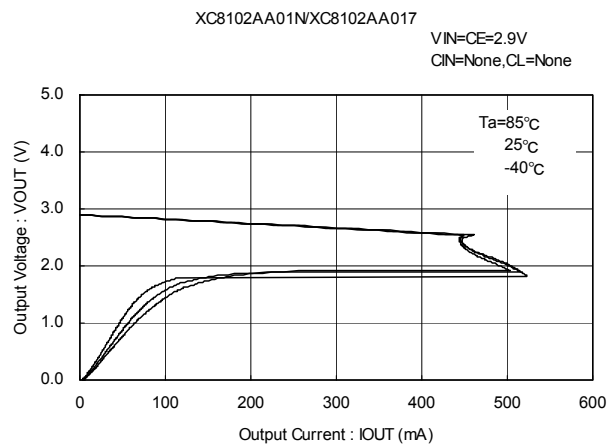
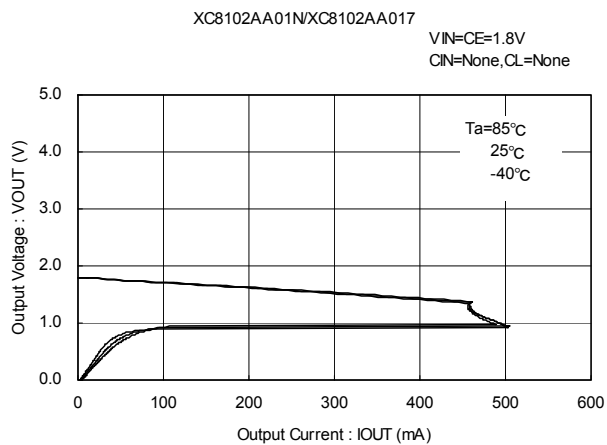
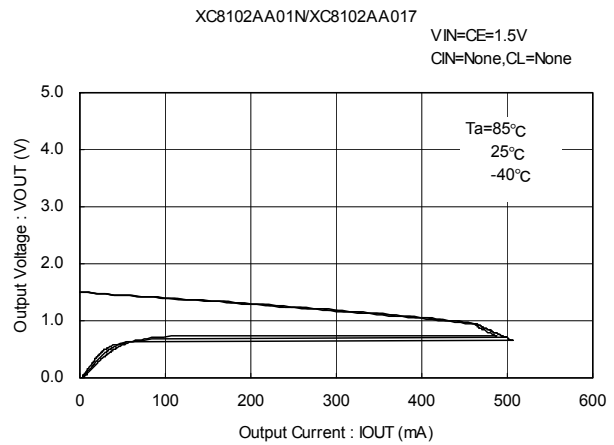
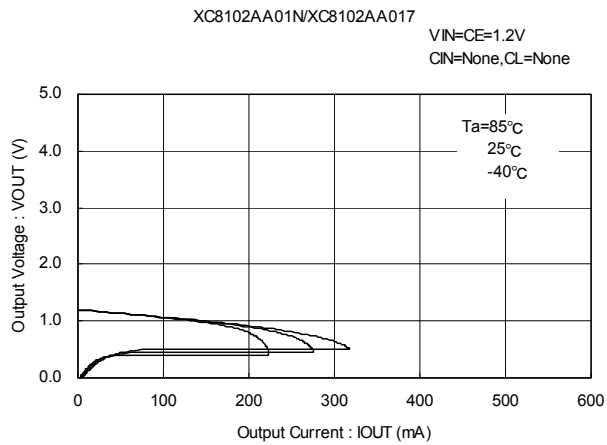
■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(5) Output Voltage vs. Output Current



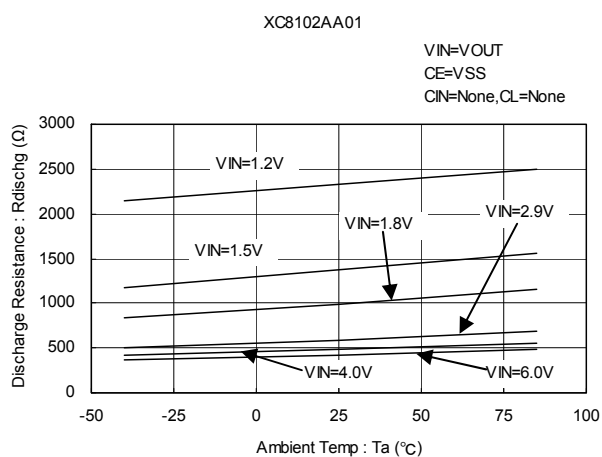
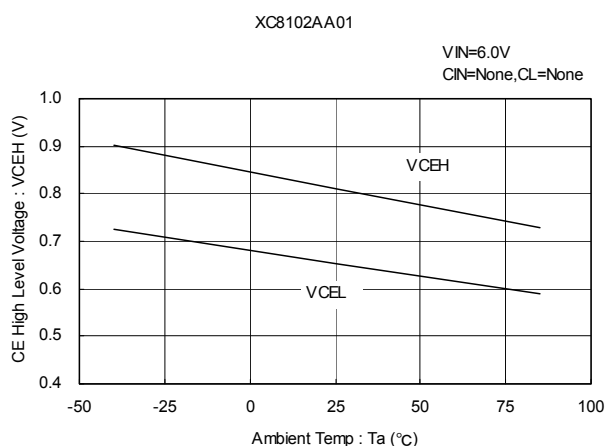
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(5) Output Voltage vs. Output Current

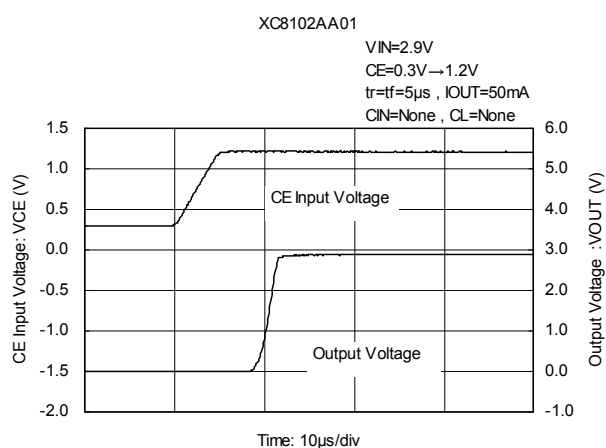
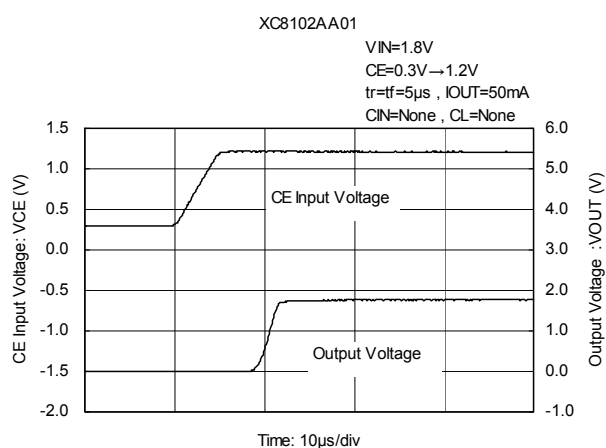
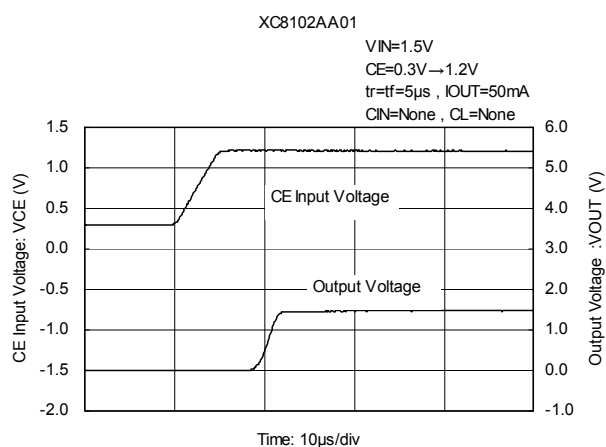
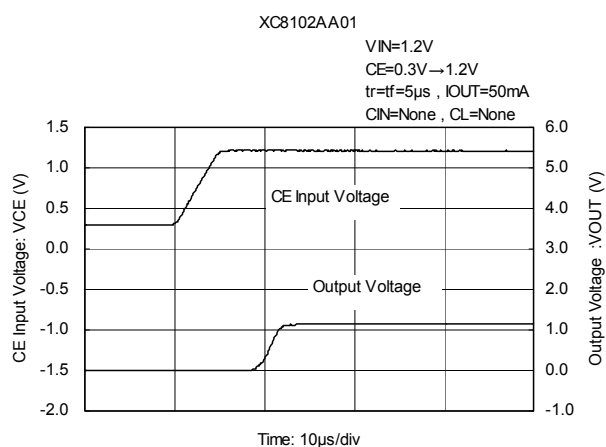


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(6) CE Threshold Voltage vs. Ambient Temperature (7) CL Discharge Resistance vs. Ambient Temperature

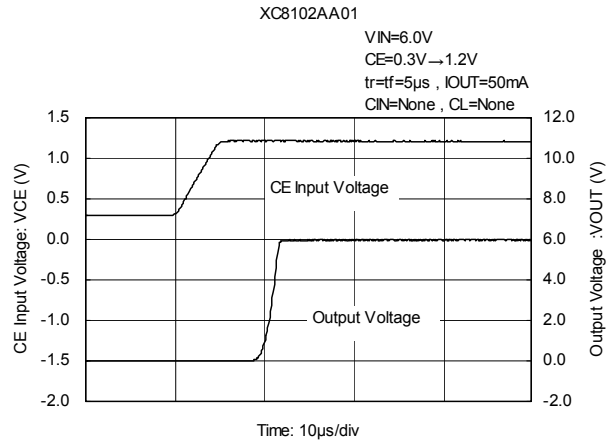
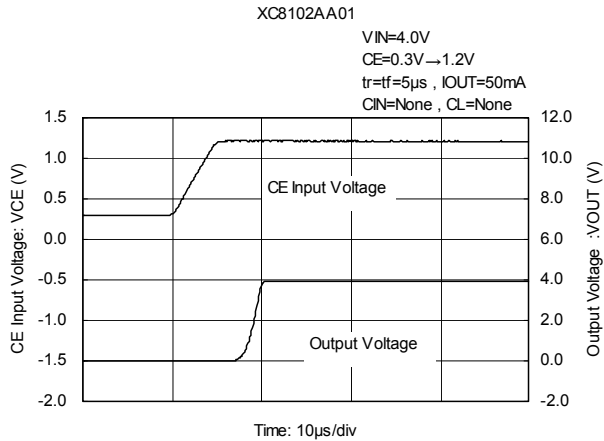


(8) Output Turn-on Time with CE

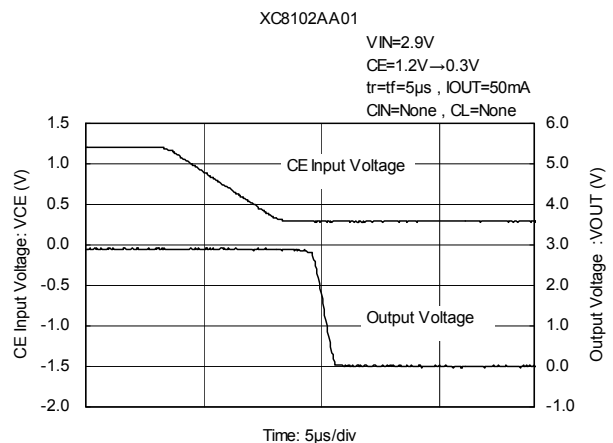
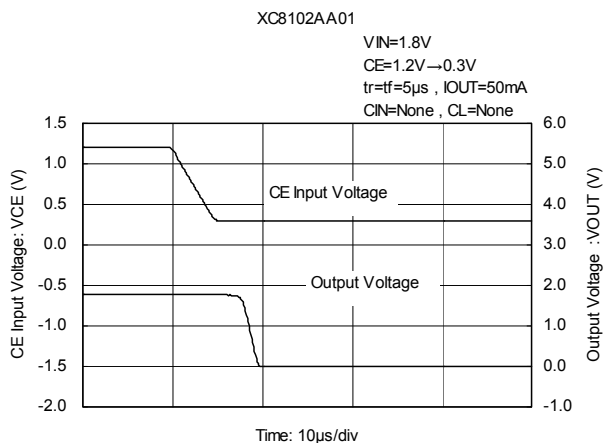
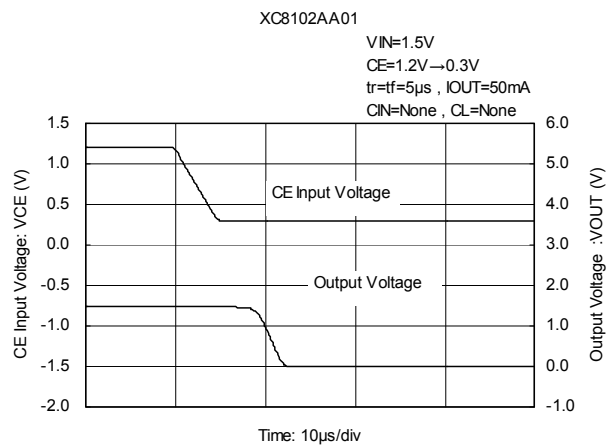
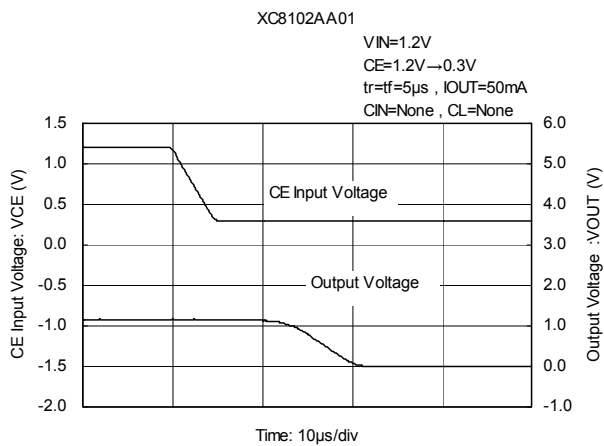


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(8) Output Turn-on Time with CE (Continued)

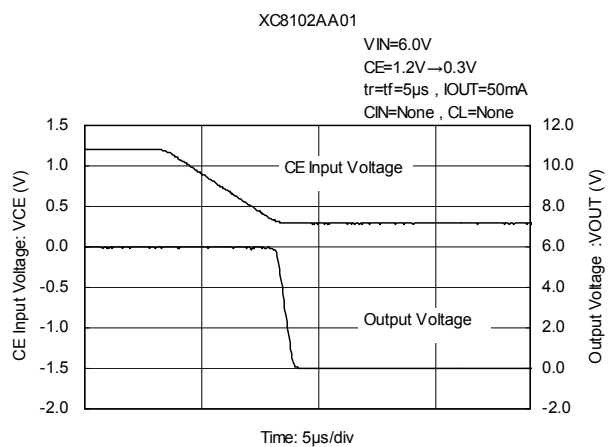
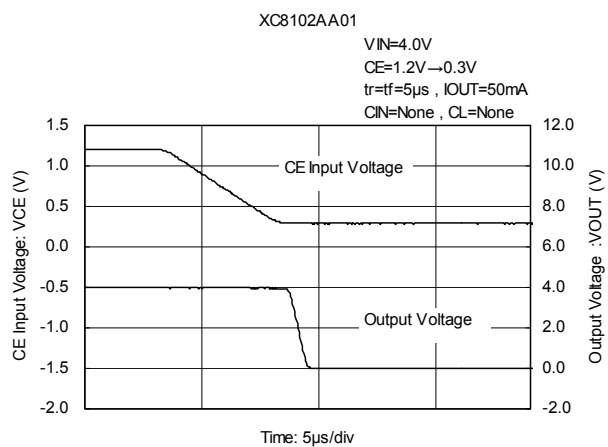


(9) Output Turn-off Time with CE



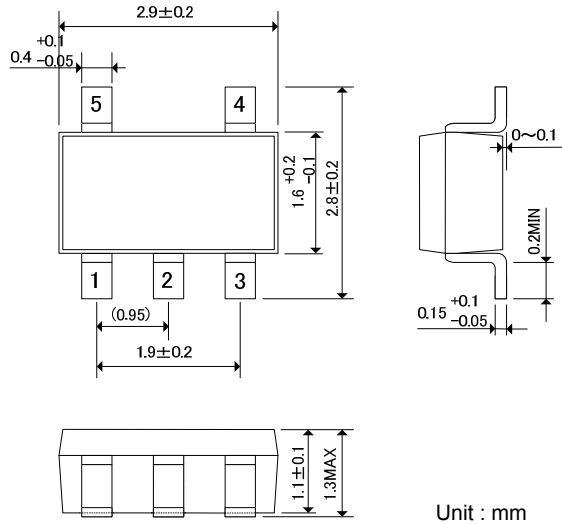
■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(9) Output Turn-off Time with CE (Continued)



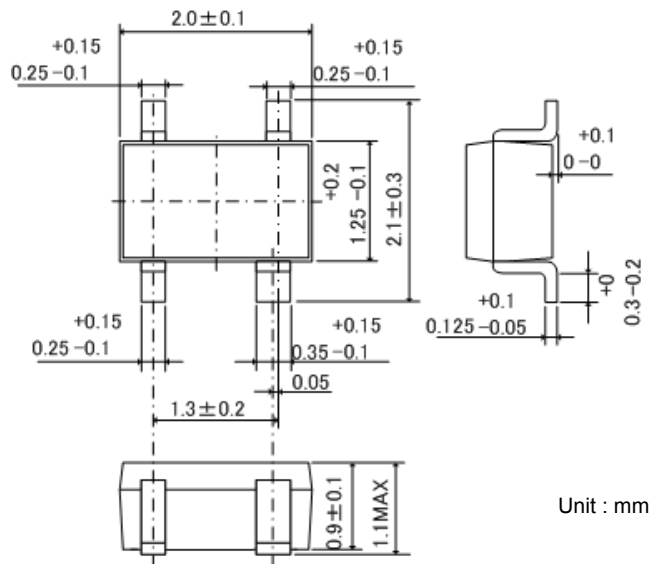
PACKAGING INFORMATION

●SOT-25



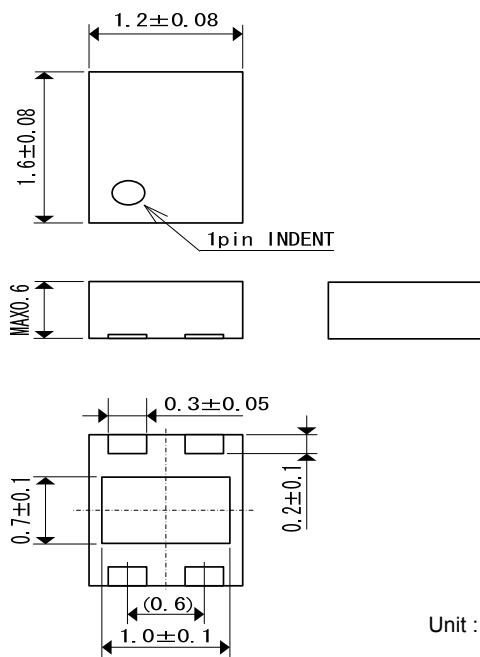
Unit : mm

●SSOT-24



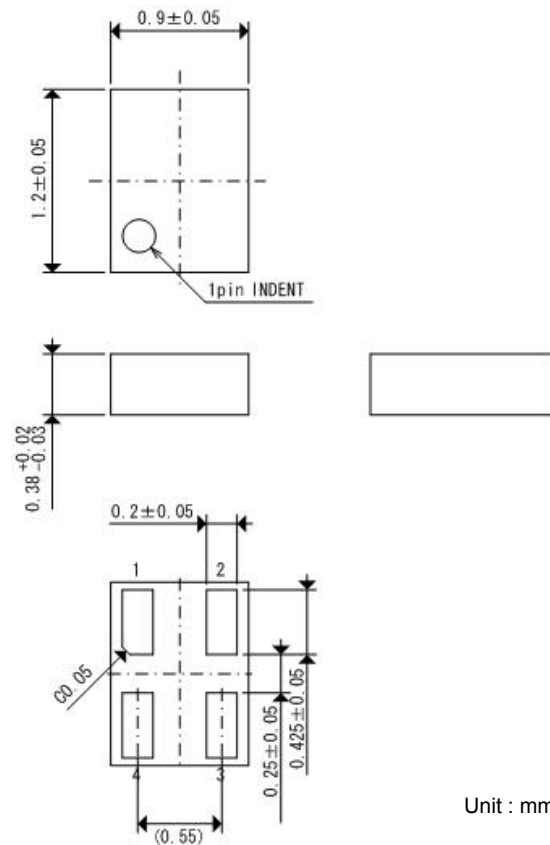
Unit : mm

●USP-4



Unit : mm

●USPN-4



Unit : mm

■ PACKAGING INFORMATION (Continued)

● SOT-25 Power Dissipation

Power dissipation data for the SOT-25 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

In top and back faces

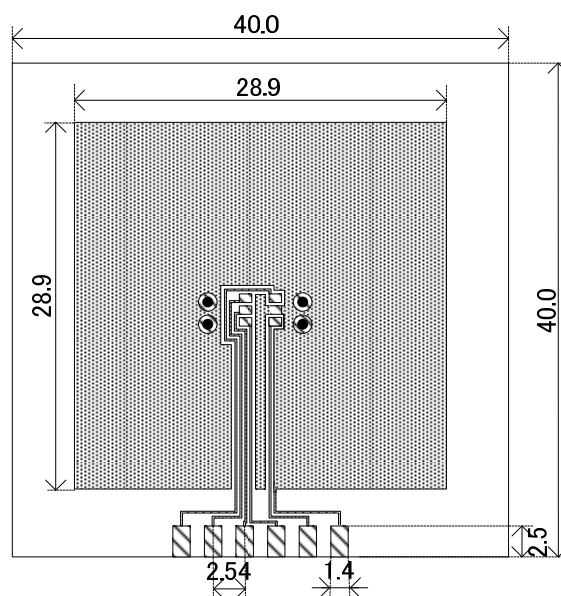
Package heat-sink is tied to the copper traces

(Board of SOT-26 is used)

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

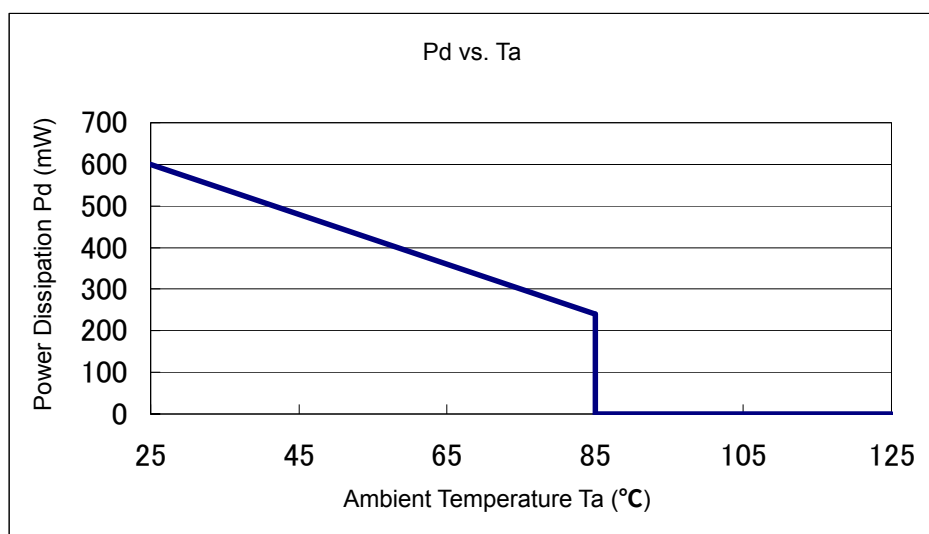


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

Ambient Temperature ($^\circ\text{C}$)	Power Dissipation P_d (mW)	Thermal Resistance ($^\circ\text{C/W}$)
25	600	166.67
85	240	



PACKAGING INFORMATION (Continued)

● SSOT-24 Power Dissipation

Power dissipation data for the SSOT-24 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

2. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

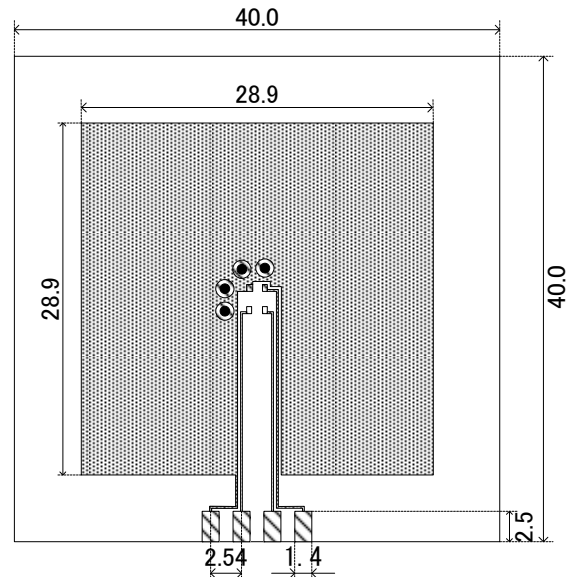
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

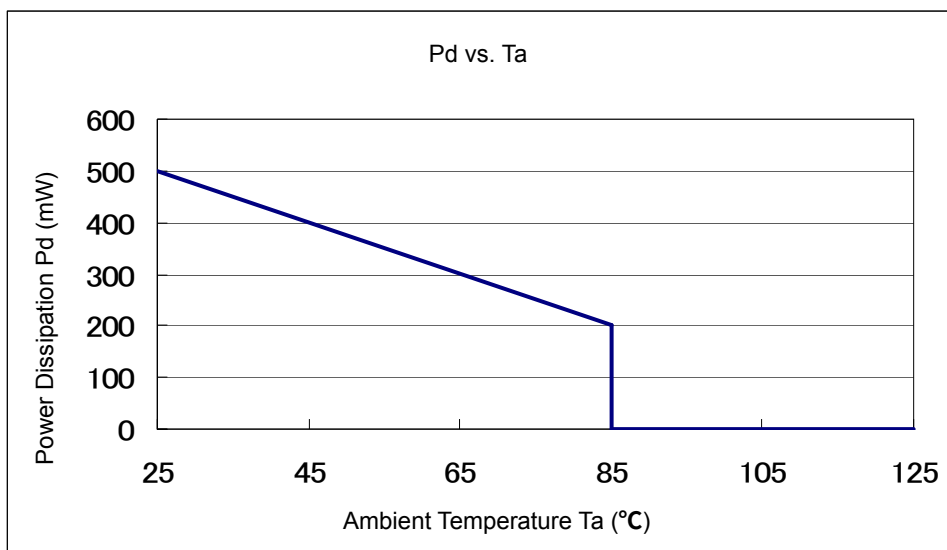


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

Ambient Temperature ($^\circ\text{C}$)	Power Dissipation P_d (mW)	Thermal Resistance ($^\circ\text{C/W}$)
25	500	200.00
85	200	



■ PACKAGING INFORMATION (Continued)

● USP-4 Power Dissipation

Power dissipation data for the USP-4 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

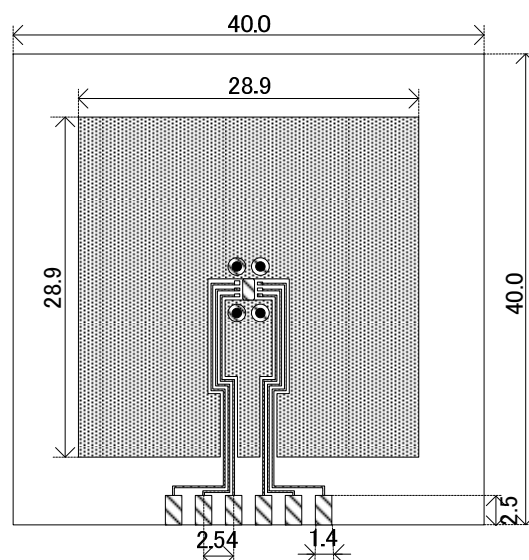
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

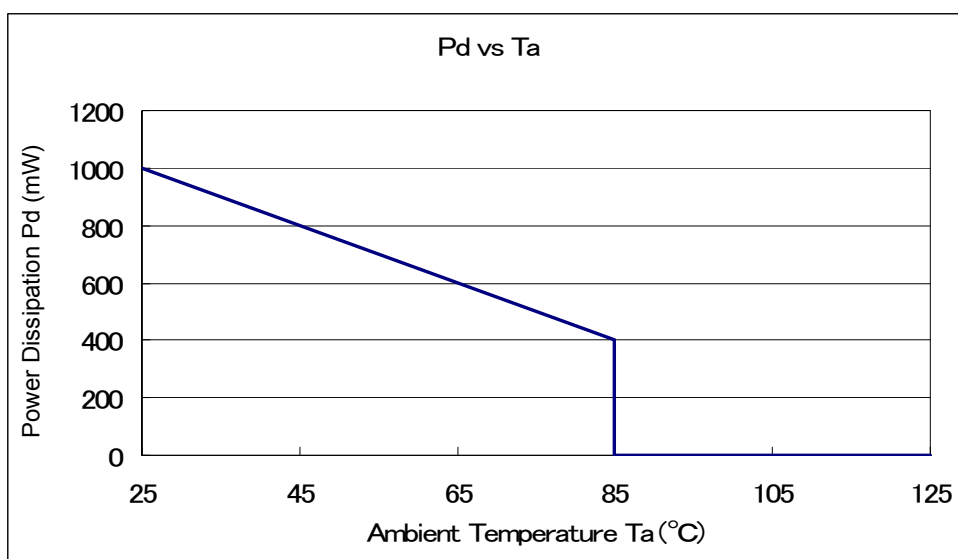


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (T_j max = 125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	100.00
85	400	



PACKAGING INFORMATION (Continued)

● USPN-4 Power Dissipation

Power dissipation data for the USPN-4 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

2. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

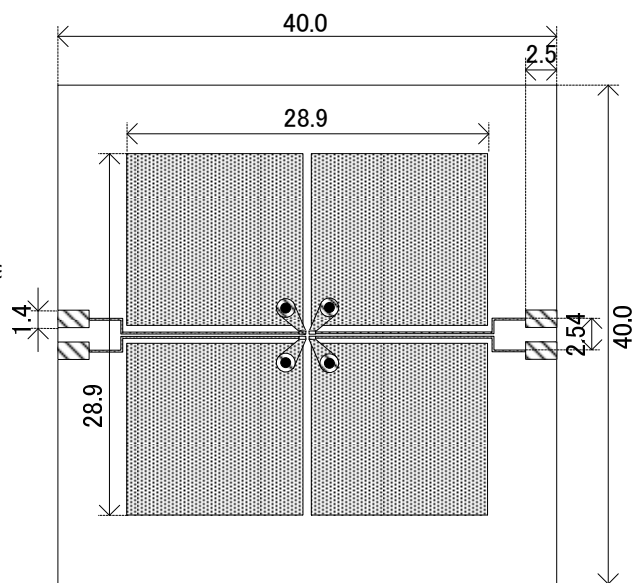
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

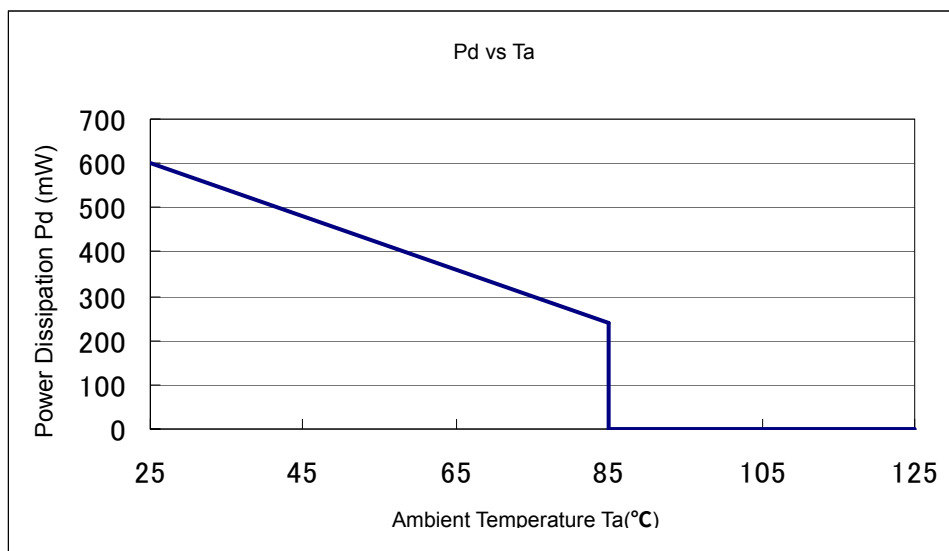


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

Ambient Temperature ($^\circ\text{C}$)	Power Dissipation P_d (mW)	Thermal Resistance ($^\circ\text{C}/\text{W}$)
25	640	166.67
85	240	



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